## What is claimed is:

- Semi-conducting thin sheet wedges comprising:

   a mica matrix, wherein said mica matrix comprises mica flakes; and
   a conductive resin impregnated within said mica matrix;

   wherein said thin sheet wedges have a semi-conductive property of between 500-500,000 ohms per square.
- 2. The semi-conducting thin sheet wedges of claim 1, wherein said thin sheet wedges have a thickness of between about 15-80 mils (0.38-2.0 mm).
- 3. The semi-conducting thin sheet wedges of claim 1, wherein said mica flakes comprise at least one of muscovite, phlogopite and combinations thereof.
- 4. The semi-conducting thin sheet wedges of claim 1,wherein said resin comprises approximately 15-40% by weight of said thin sheet wedges.
- 5. The semi-conducting thin sheet wedges of claim 1, wherein said resin is C-black.
- 6. The semi-conducting thin sheet wedges of claim 1, wherein said thin sheet wedges have a tensile modulus of between 1-8 million PSI.
- 7. The semi-conducting thin sheet wedges of claim 1, wherein said thin sheet wedges further comprises at least one glass fiber layer.
- 8. The semi-conducting thin sheet wedges of claim 7, wherein the ratio of the mica in said mica matrix to the glass fiber is approximately between 2:1 and 7:1 by weight.

- 9. The semi-conducting thin sheet wedges of claim 7, wherein said at least one glass fiber layer forms a backing for said mica matrix.
- 10. The semi-conducting thin sheet wedges of claim 7, wherein said at least one glass fiber layer is interwoven with said mica matrix.
- 11. The semi-conducting thin sheet wedges of claim 10, wherein said at least one glass fiber layer is interwoven in a half-lap manner.
- 12. Semi-conducting thin sheet wedges comprising:
  a mica matrix, wherein said mica matrix comprises mica
  flakes;

at least one layer of glass fiber; and

a conductive resin impregnated within at least one of said mica matrix and said at least one layer of glass fiber;

wherein said thin sheet wedges have a semi-conductive property of between 500-500,000 ohms per square;

wherein said thin sheet wedges have a tensile modulus of between 1-8 million PSI.

- 13. The semi-conducting thin sheet wedges of claim 12, wherein the ratio of the mica in said mica matrix to the glass fiber is approximately between 2:1 and 7:1 by weight.
- 14. The semi-conducting thin sheet wedges of claim 12, wherein said at Least one glass fiber layer forms a backing for said mica matrix.
- 15. The semi-conducting thin sheet wedges of claim 12, wherein said at least one glass fiber layer is interwoven with said mica matrix.

- 16. The semi-conducting thin sheet wedges of claim 15, wherein said at least one glass fiber layer is interwoven in a half-lap manner.
- 17. The semi-conducting thin sheet wedges of claim 12, wherein said mica flakes comprise at least one of muscovite, phlogopite and combinations thereof.
- 18. The semi-conducting thin sheet wedges of claim 12, wherein said resin comprises approximately 15-40% by weight of said thin sheet wedges.
- 19. The semi-conducting thin sheet wedges of claim 12, wherein said resin is C-black.
- 20. A method for making semi-conductive thin sheet wedges comprising:

layering a mica matrix onto a glass fiber backing, wherein said mica matrix comprises mica flakes;

impregnating into said mica matrix and said glass fiber a conductive resin; and

curing said conductive resin.